

**PALM INTRANET**

Day : Saturday  
 Date: 10/16/2004  
 Time: 18:39:21

**Inventor Name Search Result**

Your Search was:

Last Name = LEEDY

First Name = GLEN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<a href="#"><u>60402112</u></a>	Not Issued	159	08/08/2002	VERTICAL SYSTEM INTEGRATION	LEEDY, GLENN J.
<a href="#"><u>10865579</u></a>	Not Issued	030	06/09/2004	SYSTEM FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS	LEEDY, GLENN
<a href="#"><u>10766629</u></a>	Not Issued	041	01/27/2004	APPARATUS AND METHODS FOR MASKLESS PATTERN GENERATION	LEEDY, GLENN JOSEPH
<a href="#"><u>10766557</u></a>	Not Issued	019	01/27/2004	METHODS FOR MASKLESS LITHOGRAPHY	LEEDY, GLENN JOSEPH
<a href="#"><u>10742387</u></a>	Not Issued	030	12/18/2003	METHOD OF INFORMATION PROCESSING USING THREE DIMENSIONAL INTEGRATED CIRCUITS	LEEDY, GLENN J.
<a href="#"><u>10742282</u></a>	Not Issued	030	12/19/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
<a href="#"><u>10742057</u></a>	Not Issued	030	12/18/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
<a href="#"><u>10741647</u></a>	Not Issued	019	12/18/2003	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
<a href="#"><u>10741602</u></a>	Not Issued	020	12/18/2003	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY, GLENN J.
<a href="#"><u>10724031</u></a>	Not Issued	019	11/26/2003	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CIRCUIT PATTERN GENERATION	LEEDY, GLENN JOSEPH
<a href="#"><u>10700429</u></a>	Not Issued	030	11/03/2003	MEMBRANE IC FABRICATION	LEEDY, GLENN JOSEPH

<u>10672961</u>	Not Issued	030	09/26/2003	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLENN J.
<u>10665757</u>	Not Issued	030	09/19/2003	METHOD OF MAKING AN INTEGRATED CIRCUIT	LEEDY, GLENN J.
<u>10614067</u>	Not Issued	030	07/03/2003	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLEN J.
<u>10485046</u>	Not Issued	020	01/22/2004	VERTICAL SYSTEM INTEGRATION	LEEDY, GLENN J.
<u>10460483</u>	Not Issued	030	06/11/2003	STRESS-CONTROLLED DIELECTRIC INTEGRATED CIRCUIT	LEEDY, GLENN JOSEPH
<u>10460027</u>	Not Issued	092	06/11/2003	STREES-CONTROLLED DIELECTRIC INTEGRATED CIRCUIT	LEEDY, GLENN J.
<u>10385386</u>	Not Issued	041	03/07/2003	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CIRCUIT PATTERN GENERATOR	LEEDY, GLENN JOSEPH
<u>10379820</u>	Not Issued	041	03/03/2003	THREE DIMENSIONAL INTEGRATED CIRCUIT STRUCTURE HAVING A BONDING LAYER	LEEDY, GLENN J.
<u>10355558</u>	Not Issued	041	01/31/2003	METHOD AND APPARATUS FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY, GLENN J.
<u>10222816</u>	Not Issued	030	08/19/2002	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY, GLENN J.
<u>10144791</u>	<u>6563224</u>	150	05/15/2002	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT	LEEDY, GLENN J.
<u>10143200</u>	Not Issued	041	05/13/2002	RECONFIGURABLE INTEGRATED CIRCUIT MEMORY	LEEDY, GLENN J.
<u>09946552</u>	Not Issued	094	09/06/2001	METHOD AND SYSTEM FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY, GLENN
<u>09776885</u>	<u>6551857</u>	150	02/06/2001	THREE DIMENSIONAL STRUCTURE INTEGRATED	LEEDY, GLENN J.

CIRCUITS					
<u>09775670</u>	<u>6713327</u>	150	02/05/2001	STRESS CONTROLLED DIELECTRIC INTEGRATED CIRCUIT FABRICATION	LEEDY, GLENN JOSEPH
<u>09775598</u>	<u>6765279</u>	150	02/05/2001	MEMBRANE 3D IC FABRICATION	LEEDY, GLENN JOSEPH
<u>09775597</u>	<u>6682981</u>	150	02/05/2001	STRESS CONTROLLED DIELECTRIC INTEGRATED CIRCUIT FABRICATION	LEEDY, GLENN JOSEPH
<u>09607363</u>	<u>6632706</u>	150	06/30/2000	THREE DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT FABRICATION PROCESS	LEEDY, GLENN J.
<u>08813439</u>	<u>5840593</u>	150	03/10/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
<u>08488380</u>	<u>6294909</u>	150	06/07/1995	ELECTRO-MAGNETIC LITHOGRAPHIC ALIGNMENT METHOD	LEEDY , GLENN J.
<u>08486526</u>	<u>5629137</u>	150	06/07/1995	METHOD OF REPAIRING AN INTEGRATED CIRCUIT STRUCTURE	LEEDY , GLENN J.
<u>08486525</u>	Not Issued	161	06/07/1995	TESTER HEAD ASSEMBLY FOR TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
<u>08486521</u>	<u>5725995</u>	150	06/07/1995	METHOD OF REPAIRING DEFECTIVE TRACES IN AN INTEGRATED CIRCUIT STRUCTURE	LEEDY , GLENN J.
<u>08484144</u>	<u>5834334</u>	150	06/07/1995	METHOD OF FORMING A MULTI-CHIP MODULE FROM A MEMBRANE CIRCUIT	LEEDY , GLENN J.
<u>08484029</u>	<u>5592007</u>	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION TRANSISTOR FABRICATION	LEEDY , GLENN J.
<u>08483731</u>	<u>6714625</u>	150	06/07/1995	LITHOGRAPHY DEVICE FOR SEMICONDUCTOR CURCUIT PATTERN GENERATION	LEEDY , GLENN J.
<u>08483248</u>	<u>5654127</u>	150	06/07/1995	METHOD OF MAKING A TESTER SURFACE WITH HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
<u>08478476</u>	<u>5580687</u>	150	06/07/1995	A CONTACT STEPPER PRINTED LITHOGRAPHY METHOD	LEEDY , GLENN J.

<u>08477785</u>	<u>5637907</u>	150	06/07/1995	THREE DIMENSIONAL SEMICONDUCTOR CIRCUIT STRUCTURE WITH OPTICAL INTERCONNECTION	LEEDY , GLENN J.
<u>08475796</u>	<u>5592018</u>	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
<u>08475770</u>	<u>5654220</u>	150	06/07/1995	METHOD OF MAKING A STACKED 3D INTEGRATED CIRCUIT STRUCTURE	LEEDY , GLENN J.
<u>08474489</u>	<u>6288561</u>	150	06/07/1995	METHOD AND APPARATUS FOR PROBING, TESTING, BURN-IN, REPAIRING AND PROGRAMMING OF INTEGRATED CIRCUITS IN A CLOSED ENVIRONMENT USING A SINGLE APPARATUS	LEEDY , GLENN
<u>08474449</u>	<u>5571741</u>	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
<u>08474448</u>	<u>5633209</u>	150	06/07/1995	METHOD OF FORMING A CIRCUIT MEMBRANE WITH A POLYSILICON FILM	LEEDY , GLENN J.
<u>08472426</u>	<u>5946559</u>	150	06/07/1995	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
<u>08315905</u>	<u>5869354</u>	150	09/30/1994	METHOD OF MAKING DIELECTRICALLY ISOLATED INTEGRATED CIRCUIT	LEEDY , GLENN J.
<u>08217410</u>	<u>5453404</u>	150	03/24/1994	METHOD FOR MAKING AN INTERCONNECTION STRUCTURE FOR INTEGRATED CIRCUITS	LEEDY , GLENN
<u>08146470</u>	<u>5512397</u>	150	11/02/1993	STEPPER SCANNER DISCRETIONARY LITHOGRAPHY AND COMMON MASK DISCRETIONARY LITHOGRAPHY FOR INTEGRATED CIRCUITS	LEEDY , GLENN J.
<u>08055439</u>	<u>5451489</u>	150	04/30/1993	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
<u>07194596</u>	<u>4924589</u>	150	05/16/1988	METHOD OF MAKING AND TESTING AN INTEGRATED CIRCUIT	LEEDY , GLENN J.

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## Inventor Name Search Result

Your Search was:

Last Name = LEEDY

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Application#	Patent#	Status	Date Filed	Title	Inventor Name 18
<a href="#"><u>09028081</u></a>	<a href="#"><u>6008126</u></a>	150	02/23/1998	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
<a href="#"><u>09027959</u></a>	Not Issued	161	02/23/1998	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
<a href="#"><u>08971565</u></a>	<a href="#"><u>6133640</u></a>	150	11/17/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J.
<a href="#"><u>08971367</u></a>	<a href="#"><u>6208545</u></a>	150	11/17/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J.
<a href="#"><u>08850749</u></a>	<a href="#"><u>5985693</u></a>	150	05/02/1997	HIGH DENSITY THREE-DIMENSIONAL IC INTERCONNECTION	LEEDY , GLENN JOSEPH
<a href="#"><u>08835190</u></a>	<a href="#"><u>5915167</u></a>	150	04/04/1997	THREE DIMENSIONAL STRUCTURE MEMORY	LEEDY , GLENN J.
<a href="#"><u>08813439</u></a>	<a href="#"><u>5840593</u></a>	150	03/10/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN JOSEPH
<a href="#"><u>08779679</u></a>	<a href="#"><u>6020257</u></a>	150	01/07/1997	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
<a href="#"><u>08701736</u></a>	Not Issued	168	08/22/1996	MAKING AND TESTING AN INTEGRATED CIRCUIT	LEEDY , GLENN J.
<a href="#"><u>07960588</u></a>	<a href="#"><u>5323035</u></a>	150	10/13/1992	INTERCONNECTION STRUCTURE FOR INTEGRATED CIRCUITS AND METHOD FOR MAKING SAME	LEEDY , GLENN
<a href="#"><u>07865412</u></a>	<a href="#"><u>5354695</u></a>	150	04/08/1992	MEMBRANE DIELECTRIC ISOLATION IC FABRICATION	LEEDY , GLENN J.
<a href="#"><u>07838157</u></a>	Not Issued	166	02/18/1992	STEPPER SCANNER DISCRETIONARY LITHOGRAPHY AND COMMON MASK DISCRETIONARY LITHOGRAPHY FOR	LEEDY , GLENN J.

				INTEGRATED CIRCUITS	
<u>07775324</u>	<u>5225771</u>	150	10/11/1991	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
<u>07482135</u>	<u>5103557</u>	150	02/16/1990	MAKING AND TESTING AN INTEGRATED CIRCUIT USING HIGH DENSITY PROBE POINTS	LEEDY , GLENN J.
<u>07436396</u>	<u>5034685</u>	250	11/14/1989	TEST DEVICE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
<u>07436395</u>	<u>5020219</u>	150	11/14/1989	METHOD OF MAKING A FLEXIBLE TESTER SURFACE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
<u>07436278</u>	<u>4994735</u>	150	11/14/1989	FLEXIBLE TESTER SURFACE FOR TESTING INTEGRATED CIRCUITS	LEEDY , GLENN J.
<u>06661550</u>	Not Issued	161	10/15/1984	MULTIPLE PROCESSOR COMPUTER SYSTEM	LEEDY , GLENN J.

Inventor Search Completed: No Records to Display.

**Search Another:**

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GLEN

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1	BRS	15	("4500905" "4939568" "4892753" "5000113" "5240458" "5259247" "6087284" "6518073").pn.	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:14
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3	BRS	2	jp-04196263-\$ did.	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:39
4	BRS	67	("2915722" "3202948" "3559282" "3560364" "3602982" "3615901" "3716429" "3777227" "3868565" "3922705" "3997381" "4070230" "4131985" "4142004" "4251909" "4262631" "4394401" "4401986" "4416054" "4539068" "4585991" "4612083" "4617160" "4618397" "4618763" "4663559" "4684436" "4693770").pn.	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:32
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6	BRS	61	US-5151775-\$ .DID. OR US-5156909-\$ .DID. OR US-5203731-\$ .DID. OR US-5225771-\$ .DID. OR US-0523618-\$ .DID. OR US-5262351-\$ .DID. OR US-5270261-\$ .DID. OR US-5273940-\$ .DID. OR US-5274270-\$ .DID. OR US-5279865-\$ .DID. OR US-5284796-\$ .DID. OR US-5323035-\$ .DID. OR US-5324687-\$ .DID. OR US-5354695-\$ .DID. OR US-5363021-\$ .DID. OR US-5385909-\$ .DID. OR US-5385632-\$ .DID. OR US-5420458-\$ .DID. OR US-5424920-\$ .DID. OR US-5426072-\$ .DID. OR US-5426363-\$ .DID. OR US-5432444-\$ .DID. OR US-5432729-\$ .DID. OR US-5434500-\$ .DID. OR US-5451489-\$ .DID. OR US-5453404-\$ .DID. OR US-5457879-\$ .DID. OR US-5476813-\$ .DID. OR US-5489554-\$ .DID. OR US-5502667-\$ .DID. OR US-5512397-\$ .DID. OR US-5527645-\$ .DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:36

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7	BRS	50	US-5529829-\$ .DID. OR US-5534465-\$ .DID. OR US-0555512-\$ .DID. OR US-5563084-\$ .DID. OR US-5571741-\$ .DID. OR US-5580687-\$ .DID. OR US-5581498-\$ .DID. OR US-5582939-\$ .DID. OR US-5583688-\$ .DID. OR US-5592007-\$ .DID. OR US-5592018-\$ .DID. OR US-5595933-\$ .DID. OR US-5606186-\$ .DID. OR US-0562712-\$ .DID. OR US-5629137-\$ .DID. OR US-5633209-\$ .DID. OR US-5637536-\$ .DID. OR US-5654127-\$ .DID. OR US-5654220-\$ .DID. OR US-5656552-\$ .DID. OR US-5675185-\$ .DID. OR US-5694588-\$ .DID. OR US-5725995-\$ .DID. OR US-0575021-\$ .DID. OR US-5760478-\$ .DID. OR US-5773152-\$ .DID. OR US-0578616-\$ .DID. OR US-0579315-\$ .DID. OR US-5831280-\$ .DID. OR US-5834334-\$ .DID. OR US-5840593-\$ .DID. OR US-5856695-\$ .DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:37

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14	BRS	1	gb-2215168-\$ .did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:41
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18	BRS	1	wo-9719337-\$ .did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:43
19	BRS	1	jp-02027600-\$ .did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:03
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21	BRS	530	438/459.cccls. and 257/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
22	BRS	432	438/977.cccls. and 257/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
23	BRS	544	438/109.cccls. and 257/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
24	BRS	60	(438/455.cccls. and 257/\$.cccls.) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
25	BRS	216	(438/455.cccls. and 257/\$.cccls.) and substrates with (bond bonding bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
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27	BRS	2	((438/455.cccls. and 257/\$.cccls.) and substrates with (bond bonding bonded)) and plurality with substrates and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
28	BRS	213	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:44

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29	BRS	9	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:20
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32	BRS	4	("5324687" "5563084").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:14
33	BRS	32	substrates with (bond bonding bonded) and plurality with substrates and thermal adj (diffusion diffuse diffused diffusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
34	BRS	88	substrates with (bond bonding bonded) and plurality with substrates and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
35	BRS	0	(substrates with (bond bonding bonded) and plurality with substrates and thermal adj (diffusion diffuse diffused diffusing)) and conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:20
36	BRS	0	substrates with (bond bonding bonded) and plurality with substrates same thermal adj (diffusion diffuse diffused diffusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
37	BRS	8	substrates with (bond bonding bonded) and plurality with substrates same conductive adj paths	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:21
38	BRS	33	(438/459.ccls. and 257/\$.ccls.) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23
39	BRS	164	(438/459.ccls. and 257/\$.ccls.) and substrates with (bond bonding bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:23

	Type	Hits	Search Text	DBs	Time Stamp
40	BRS	33	((438/459.ccls. and 257/\$.ccls.) and plurality with substrates) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
41	BRS	2	((438/459.ccls. and 257/\$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates) and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:24
42	BRS	2	((438/459.ccls. and 257/\$.ccls.) and plurality with substrates) and plurality with substrates) and flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:25
43	BRS	23	((438/459.ccls. and 257/\$.ccls.) and substrates with (bond bonding bonded)) and plurality with substrates	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:25
44	BRS	67	substrates with (bond bonding bonded) and plurality with substrates and flexible adj substrate and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:46
45	BRS	1598	257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
46	BRS	138	257/74.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
47	BRS	1980	257/723.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52
48	BRS	1543	257/724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:52